PATENT CLAIMS

 A method for producing an optically effective system of layers on a substrate having a first side and a second side, comprising the steps of

5

10

15

20

25

30

applying a protective layer to the second side of the substrate by means of a sputter deposition process, or selecting a substrate which has had a protective layer already applied to the second side thereof, and then

applying a system of layers to the first side of the substrate by means of a sputter deposition process.

- 2. The method as claimed in claim 1, wherein the protective layer is formed by a single layer or by an additional system of layers applied to the second side.
- 3. The method as claimed in claim 1, wherein after the system of layers has been applied on the first side, a further system of layers is applied onto the second side by means of a sputter deposition process.
- 4. The method as claimed in claim 3, wherein the protective layer is selected or produced in such a manner that its optical properties are matched to the conditions which are to be satisfied by the further system of layers.
- 5. The method as claimed in claim 1, wherein the protective layer is applied onto the second side by means of a sputter deposition process.
- 6. The method as claimed in claim 5, wherein the protective layer is applied using a substantially oxygen-free plasma sputter deposition process.

Atty Dkt: 034183/268724

5

20

25

30

7. The method as claimed in claim 5, wherein the protective layer is applied using the same target in the sputter deposition process which is also used to produce at least some layers of the system of layers applied on the first side and/or at least some of the layers of the further system of layers applied on the second side.

16

- 8. The method as claimed in claim 7, wherein the

 same target is used to produce the protective layer and
 the system of layers applied on the first side and/or the
 further system of layers applied on the second side, and
 with the process gas used in the sputter deposition
 processes in forming the layers of the systems of layers
 being selected as a function of the layer which is to be
 produced.
 - 9. The method as claimed in claim 1, wherein the composition of the protective layer is selected from the group consisting of silicon oxide, silicon nitride, aluminum oxide and/or aluminum nitride.
 - 10. The method as claimed in claim 1, wherein the protective layer is applied with a thickness of 10 to 40 nm.
 - 11. The method as claimed in claim 1, wherein the material of the protective layer and its thickness are selected in such a way, as a function of the process parameters during application of the system of layers to the front side, that after this layer system has been applied, the protective layer has a predetermined thickness.

12. The method as claimed in claim 1, wherein the step of applying a protective layer to the second side of the substrate includes applying a system of layers which acts as a protective layer, and wherein the first side is initially machined in order to obtain predetermined optical properties, and then the system of layers is applied to the first side.

5

- effective system of layers on a substrate having a first side and a generally parallel second side, comprising an evacuable sputter chamber and a substrate holder with receiving elements for substrates, with each receiving element being mounted so that each substrate can be rotated both about a turning axis, which is oriented substantially parallel to the substrate sides, and about an axis of rotation, which is oriented substantially perpendicularly to the substrate sides.
- 20 14. The apparatus as claimed in claim 13, further comprising a common drive for the rotary movement and the turning movement.

Atty Dkt: 034183/268724